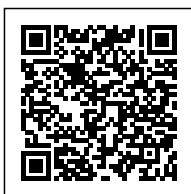


## CHEMICAL TINNING PLANT | BUNGARD PROTEC SN



SKU: PROTEC-SN



### BUNGARD PROTEC 2030/2040

PROTEC SN – Professional equipment for the **production of final surfaces on printed circuit boards**.  
The machine includes all the necessary tanks and electrical equipment in a very compact design.

#### Available models:

- **PROTEC 2030**  
Max. board size: **200 x 300 mm**  
Teflon heating elements: 2 pieces x 400W  
Tank volume: 10L  
Dimensions (LxWxH): ca. 790 x 710 x 1160 mm  
Power supply: Single-phase 230V, AC.
- **PROTEC 3040**  
Max. board size: **300 x 400 mm**  
Teflon heating elements: 2 pieces x 800W  
Tank volume: 20L  
Dimensions (LxWxH): ca. 790 x 810 x 1160 mm  
Power supply: Single-phase 230V, AC.



## Features

- **TANK 1 | Microetch** – With ball cock outlet valve, cover, timer
- **TANK 2 | Spray / Rinsing** – Regulated by an angle seat solenoid valve, with ball cock outlet valve
- **TANK 3 | Organic metal** – With ball cock outlet valve, cover, timer
- **TANK 4 | Chemical tin 7001** – With PTFE heating element thermostatically regulated 20-80°C, ball cock outlet valve, cover, timer
- **TANK 5 | Warm rinsing** – With stainless steel heating element thermostatically regulated 20-50°C, ball cock outlet valve, cover, timer
- Underframe (plastic), control unit with main switch
- PCB holder.

## Advantages

**Tin layers** which have been created with the Protec ORMECON® process guarantee:

- **Planar surface** for SMD technology
- **Pure tin deposit**, even with high copper load of the bath
- Significant **reduction of diffusion velocity**
- Possibility of **multiple soldering**, even with intermediate storage
- Improved **temperature resistance**.

The design of PROTEC SN allows easy modifications. By **adding or skipping tanks** you can adapt the PROTEC to the requirements of the following processes:

- **Electroless Nickel / Electroless Gold**
- **OSP** (Organic Solderability Preservative).